



PCN Number:	PCN20150310002	PCN Date:	03/13/2015				
Title:	Qualification of Vanguard Facility as an additional FAB site source for selected devices in the 0.60UM process						
Customer Contact:	PCN Manager	Dept:	Quality Services				
*Proposed 1st Ship Date:	06/13/2015	Estimated Sample Availability:	Date provided at sample request				
Change Type:							
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process				
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification				
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling				
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material				
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials				
<input type="checkbox"/>		<input type="checkbox"/>	Part number change				
PCN Details							
Description of Change:							
Texas Instruments is pleased to announce the qualification of its Vanguard fabrication facility as an additional wafer FAB source for the selected devices listed in "Product Affected" section.							
Currently Qualified Sites, Process, wafer dia.		Additional Site, Process, wafer dia.					
TSMC-WF2, 0.60UM, 200mm		Vanguard, VIS 0.6UM DPDM, 200mm					
The 0.6um DPDM process has been running in production successfully in Vanguard since 2006. Qualification details are provided in the Qual Data Section.							
Reason for Change:							
Continuity of Supply							
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):							
None							
Changes to product identification resulting from this PCN:							
Current							
Chip Site	Chip site code (20L)	Chip country code (21L)					
TSMC-WF2	TS2	TWN					
New							
Chip Site	Chip site code (20L)	Chip country code (21L)					
Vanguard (VIS)	VAN	TWN					
Sample product shipping label (not actual product label)							
 MADE IN: Malaysia 2DC: 20: <table border="1"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> OPT: ITEM: LBL: 5A (L)T0:1750		MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04	 (1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO:USA (22L) AS0:MLA (23L) AG0:THS	
MSL 2 /260C/1 YEAR	SEAL DT						
MSL 1 /235C/UNLIM	03/29/04						

Product Affected:

OPA2364AID	OPA2364AIDGKT	OPA2364ID	OPA2364IDGKTG4
OPA2364AIDG4	OPA2364AIDGKTG4	OPA2364IDGKR	OPA2364IDR
OPA2364AIDGKR	OPA2364AIDR	OPA2364IDGKRG4	OPA2364IDRG4
OPA2364AIDGKRG4	OPA2364AIDRG4	OPA2364IDGKT	

Qualification Report

**OPA2364 Vanguard (aka VIS FAB - qualified process flow 0.5um/0.6um) model
transfer from TSMC FAB2
Approved 01/23/2015**

Attributes		Qual Device: OPA2364AIDGK	QBS Process: DDC112Y	QBS Process: OPA343U	QBS Process: TSC2046IPW
Assembly Site		ASE SHANGHAI	CRS	OSE	TAI
Package Family		VSSOP	TQFP	SOIC	TSSOP
Flammability Rating		UL 94 V-0	UL94 Class V-0	UL94 Class V-0	UL94 Class V-0
Wafer Fab Site		VANGUARD-8	VANGUARD	VANGUARD	VANGUARD
Wafer Fab Process		0.6/0.5um DPDM	0.5/0.6um DPDM	0.5/0.6um DPDM	0.5/0.6um DPDM
Test Name / Condition	Duration	Qual Device: OPA2364AIDGK	QBS Process: DDC112Y	QBS Process: OPA343U	QBS Process: TSC2046IPW
Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	-	1/77/0
Autoclave 121C	96 Hours	-	1/77/0	1/77/0	1/77/0
Temperature Cycle, - 65/150C	500 Cycles	3/231/0	1/77/0	1/77/0	1/77/0
High Temp. Storage Bake, 150C	1000 Hours	-	1/77/0	-	-
High Temp. Storage Bake, 170C	420 Hours	-	-	-	1/77/0
Thermal Shock -65/150C	500 Cycles	-	1/77/0	-	1/77/0
Life Test, 125C	1000 Hours	-	-	-	-
Life Test, 150C	300 Hours	3/231/0	1/77/0	1/77/0	1/77/0
ESD - HBM	2500 V	2/6/2000	-	-	-
ESD - CDM	1000 V	3/9/2000	1/3/2000	-	1/3/2000
Latch-up	(per JESD78)	3/18/2000	1/6/2000	1/6/2000	1/6/2000
Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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